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MC11608A6WK1-SPTLY 1 x 16		8mm Character Height	LCD Module							
Specification										
Version: 5		Date: 29/10/2018								
		Revision								
1	30/10/2009	First issue.								
2	22/11/2013	Correct Contour Drawing Modify ST7066U IC Backlight Information.	information Modify							
3	12/08/2014	Remove IC information.								
4	25/02/2016									
5	29/10/2018	Modify Backlight Information.								

Display F			
Character Count	1 x 16		
Appearance	Black on Yellow/Green		
Logic Voltage	5V		
Interface	Parallel		1
Font Set	English / European		ROHS ompliant
Display Mode	Transflective		ampliant
Character Height	8.06mm	C	ompliant
LC Type	STN		
Module Size	122.00 x 33.00 x 13.50mm		
Operating Temperature	-20°C ~ +70°C		
Construction	COB	Box Quantity	Weight / Display
LED Backlight SIGN	MANUFACYellow	RE -SUP	PLY

* - For full design functionality, please use this specification in conjunction with the ST7066U specification. (Provided Separately)

Description

Optional Variants									
Fonts	Appearances	Voltage							

General Specification

The Features is described as follow:

■ Module dimension: 122.0 x 33.0 x 13.5 (max.) mm

View area: 99.0 x 13.0 mm

Active area: 94.84 x 9.66 mm

■ Number of Characters: 16 characters x 1Lines

■ Dot size: 0.92 x 1.1 mm

■ Dot pitch: 0.98 x 1.16 mm

■ Character size: 4.84 x 8.06 mm

■ Character pitch: 6.0 x 8.56 mm

■ LCD type: STN Positive, Yellow Green Transflective

■ Duty: 1/16

■ View direction: 6 o'clock

■ Backlight Type: LED, Yellow Green

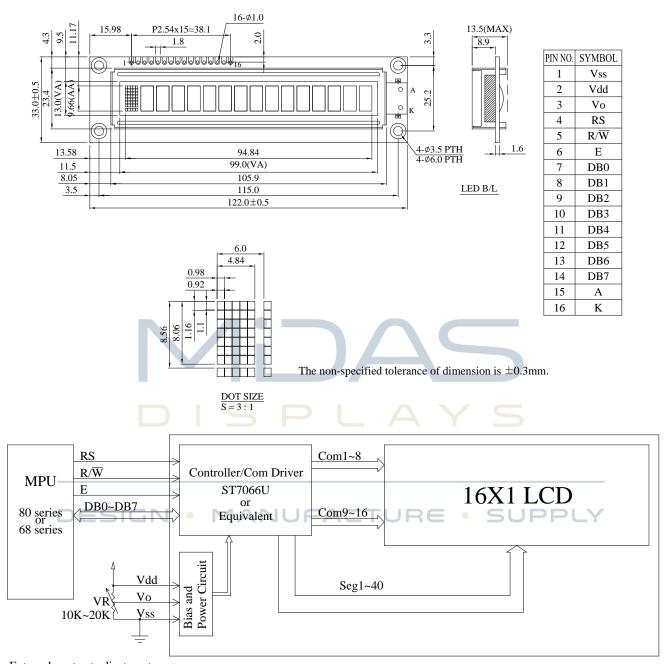
■ IC: ST7066U

DESIGN • MANUFACTURE • SUPPLY

Interface Pin Function

Pin No.	Symbol	Level	Description
1	Vss	0V	Ground
2	V_{DD}	5.0V	Supply Voltage for logic
3	VO	(Variable)	Operating voltage for LCD
4	RS	H/L	H: DATA, L: Instruction code
5	R/W	H/L	H: Read (Module> MPU) L: Write(MPU> Module)
6	E	H,H→L	Chip enable signal
7	DB0	H/L	Data bit 0
8	DB1	H/L	Data bit 1
9	DB2	H/L	Data bit 2
10	DB3	H/L	Data bit 3
11	DB4	H/L	Data bit 4
12	DB5	H/L	Data bit 5
13	DB6	H/L	Data bit 6
14	DB7	H/L	Data bit 7
15	А	_	Power supply for B/L(+)
16	К		Power supply for B/L(-)

Contour Drawing & Block Diagram



External contrast adjustment.

Character located 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 DDRAM address 00 01 02 03 04 05 06 07 40 41 42 43 44 45 46 47

2-line display mode.

Character Generator ROM Pattern

Table.2

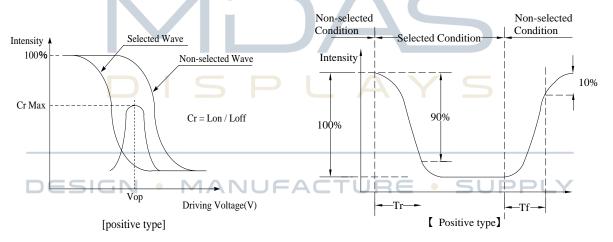
Upper																
4 bit Lower 4 bit	LLLL	LLLH	LLHL	LLHH	LHLL	LHLH	LHHL	СННН	HLLL	HLLH	HLHL	нцнн	HHLL	ннцн	нннг	нннн
LLLL	CG RAM (1)	[==	===-			-:::1	=				
LLLH	CG RAM (2)			-1			-:::1	-225	 !!			* *			*===	
LLHL	CG RAM (3)	= = =		-"-:			! !	1			=;;;;	-:-	=====			
LLHH	CG RAM (4)				====	-,,,,	====		-:::	=====	 !!	*_	=		====	
LHLL	CG RAM (5)	#		=:-[-					-:::	=====			-=[-		=======================================	1,:,1
LHLH	CG RAM (6)		"==			II	====	I[-:::1	=,		I		1		
LHHL	CG RAM (7)	=======================================				I.,.I		1	-:::1	<i>-</i>			[
LHHH	CG RAM (8)		==	=======================================			-:::	1	====	 !!]:-:[::	; ² :	1	
HLLL	CG RAM (1)		! ".			<u>:::</u> ;	ļ _i	[:-:]		=	===		-1;		[-:]	
HLLH	CG RAM (2)	- - - - - -				-,.	1	= ::; =			i	-="			.,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	
HLHL	CG RAM (3)		[11			-,			[]]	
НЦНН	CG RAM (4)			==			Ĭ-:".		***	!-";	-:::	-::::		="="=	Į_:=	
HHLL	CG RAM (5)	****	: =	-:-		****]:::-			=====	
HHLH	CG RAM (6)	="=,=							**		=====		==			=====
нннг	CG RAM (7)		==		=-=	".,	i-"i			11						
нннн	CG RAM (8)							=====		====	=	***			ii.	

Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧2	0	_	20	ψ= 180°
View Angle	θ	CR≧2	0	_	40	ψ= 0°
View Angle	θ	CR≧2	0	_	30	ψ= 90°
	θ	CR≧2	0	_	30	ψ= 270°
Contrast Ratio	CR	_	_	3	_	_
	T rise	_	_	150	200	ms
Response Time	T fall	_	_	150	200	ms

Definition of Operation Voltage (Vop)

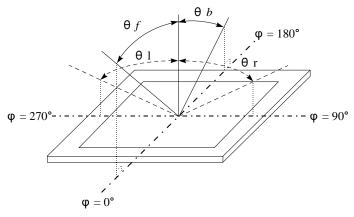
Definition of Response Time (Tr , Tf)



Conditions:

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle(CR≧2)



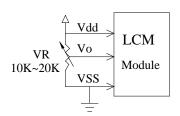
Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	°C
Storage Temperature	T _{ST}	-30	_	+80	°C
Input Voltage	Vı	Vss	_	V_{DD}	V
Supply Voltage For Logic	VDD-VSS	-0.3	_	7	V
Supply Voltage For LCD	V _{DD} -V _o	-0.3	_	13	V

Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V _{DD} -V _{SS}		4.5	5.0	5.5	V
Supply Voltage For LCD *Note	V _{DD} -V ₀	Ta=-20°C J Ta=25°C	4.2	4.35	5.5 4.5	\ \ \
		Ta=70°C	3.5	_	_	V
Input High Volt.	Vih	_	0.7 V _{DD}	_	V_{DD}	V
Input Low Volt.	VIL		Vss		0.6	V
Output High Volt.	Vон	l	3.9	١	Vdd	V
Output Low Volt.	V_{OL}	_	0	_	0.4	V
Supply Current	I _{DD}	V _{DD} =5.0V	1.0	1.2	1.5	mA

^{*} Note: Please design the VOP adjustment circuit on customer's main board



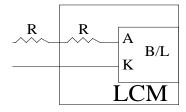
Backlight Information

Specification

PARAMETER	SYMBOL	MIN	TYP	мах	UNIT	TEST CONDITION
Supply Current	ILED	128	160	192	mA	V=4.2V
Supply Voltage	V	3.8	4.2	4.6	v	_
Reverse Voltage	VR	_	_	5	v	_
Luminance (Without LCD)	IV	150	210	_	CD/M ²	ILED=160mA
Wave Length	λр	569	571	573	nm	ILED=160mA
Life Time	-\/	1 i	50000	-/	Hr.	ILED≦160mA 25℃,50-60%RH
Color	Yellow Gro	een			2 \	

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

2.Drive from pin15,pin16



ill never get Vee output from pin15)

Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

	Environmental Test								
Test Item	Content of Test	Test Condition	Note						
High Temperature storage	Endurance test applying the high storage temperature for a long time.	200hrs	2						
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2						
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs							
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1						
High Temperature/ Humidity storage	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2						
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles							
	ISPLAY	Total fixed amplitude : 1.5mm							
Vibration test	Endurance test applying the vibration during transportation and using.	Vibration Frequency : 10~55Hz	3						
DESIGN	• MANUFACTURE •	One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes							
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330 Ω CS=150pF 10 times							

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

Inspection specification

NO	Item	Criterion								
01	Electrical Testing	defect. 1.2 Missing cha 1.3 Display malf 1.4 No function 1.5 Current cons 1.6 LCD viewing 1.7 Mixed produ 1.8 Contrast def	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 2.1 White and black spots on display ≤ 0.25mm, no more than 							
02	Black or white spots on LCD (display only)	three white o	or black sp			2.5				
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type $\Phi = (x + y) / $ 3.2 Line type : (A	2 ↓ Y \ 0	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2 1 0 SUPPLY Acceptable Q TY Accept no dense 2 As round type	2.5				
04	Polarizer bubbles	If bubbles are vi judge using blace specifications, no to find, must che specify direction	ck spot oot easy eck in	Size Φ $ Φ \le 0.20 $ $ 0.20 < Φ \le 0.50 $ $ 0.50 < Φ \le 1.00 $ $ 1.00 < Φ $ $ Total Q TY$	Acceptable Q TY Accept no dense 3 2 0 3	2.5				

NO	Item	Criterion					
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination					
		Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length: 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:					
06	Chipped glass	z: Chip thickness $Z \le 1/2t$ $1/2t < z \le 2t$ $\odot \text{ If there are 2 or more}$	y: Chip width Not over viewing area Not exceed 1/3k chips, x is total length of	x: Chip length x≤1/8a x≤1/8a of each chip.	2.5		
		6.1.2 Corner crack:					
	DESIGI	N · MANI					
		z: Chip thickness	y: Chip width	x: Chip length			
		Z≦1/2t	Not over viewing area	x≦1/8a			
		1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a			
		⊙If there are 2 or more	chips, x is the total leng	gth of each chip.			

NO	Item	Criterion				
	Glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:				
06		$\begin{array}{ c c c c c c }\hline y: Chip \ width & x: Chip \ length & z: Chip \ thickness \\\hline y \le 0.5 mm & x \le 1/8a & 0 < z \le t \\\hline 6.2.2 \ Non-conductive \ portion: \\\hline \end{array}$				
	DES	y: Chip width x: Chip length z: Chip thickness y ≤ L x ≤ 1/8a 0 < z ≤ t Olf the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. Olf the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length y ≤ 1/3L x ≤ a				

NO	Item	Criterion	AQL	
07	Cracked glass	ass The LCD with extensive crack is not acceptable.		
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 		
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65	
		 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than 	2.5 2.5 0.65 2.5	
10	PCB · COB	three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.	2.5 0.65	
[DESIGN	 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB X * Y<=2mm2 	0.65 2.5 2.5	
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65	

NO	Item	Criterion		
	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.12.2 No cracks on interface pin (OLB) of TCP.		
		12.3 No contamination, solder residue or solder balls on product.	0.65 2.5	
		12.4 The IC on the TCP may not be damaged, circuits.		
		12.5 The uppermost edge of the protective strip on the interface	2.5	
		pin must be present or look as if it cause the interface pin to sever.	2.5	
12		12.6 The residual rosin or tin oil of soldering (component or chip		
12		component) is not burned into brown or black color.		
		12.7 Sealant on top of the ITO circuit has not hardened.		
		12.8 Pin type must match type in specification sheet.	0.65	
		12.9 LCD pin loose or missing pins.	0.65	
		12.10 Product packaging must the same as specified on		
		packaging specification sheet.	0.65	
		12.11 Product dimension and structure must conform to product		
		specification sheet.		
		12.12 Visual defect outside of VA is not considered to be rejection.		

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Precautions in use of LCD Modules

- Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- Don't disassemble the LCM. (3)
- (4) Don't operate it above the absolute maximum rating.
- Don't drop, bend or twist LCM. (5)
- Soldering: only to the I/O terminals. (6)
- Storage: please storage in anti-static electricity container and clean environment. (7)
- (8) MIDAS have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) MIDAS have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, MIDAS have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.

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Material List of Components for RoHs

1. MIDAS hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

- 2.Process for RoHS requirement: (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.

Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.